**Recommended Solder Pad Pitch and Dimensions**

1. **1.30 ± 0.05** (4 SIDES)
2. **2.10 ± 0.05**
3. **3.50 ± 0.05**
4. **0.70 ± 0.05**
5. **0.25 ± 0.05**
6. **0.50 BSC**

**Package Outline**

- **3.00 ± 0.05** (4 SIDES)
- **0.65 ± 0.05**

**Note:**

1. Drawing not to scale
2. All dimensions are in millimeters
3. Dimensions of exposed pad at bottom of package do not include mold flash. Mold flash, if present, shall not exceed 0.15mm on any side.
4. Exposed pad shall be solder plated.
5. Shaded area is only a reference for pin 1 location on the top and bottom of package.

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**Recommended Solder Pad Pitch and Dimensions**